Lattice Semiconductor Corporation - LFSCM3GA25EP1-5FFA1020I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	6250
Number of Logic Elements/Cells	25000
Total RAM Bits	1966080
Number of I/O	476
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFcBGA Rev 2 (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga25ep1-5ffa1020i

Table 1-1. LatticeSC Family Selection Guide[1]

Device	SC15	SC25	SC40	SC80	SC115
LUT4s (K)	15	25	40	80	115
sysMEM Blocks (18Kb)	56	104	216	308	424
Embedded Memory (Mbits)	1.03	1.92	3.98	5.68	7.8
Max. Distributed Memory (Mbits)	0.24	0.41	0.65	1.28	1.84
Number of 3.8Gbps SERDES (Max.)	8	16	16	32	32
DLLs	12	12	12	12	12
Analog PLLs	8	8	8	8	8
MACO Blocks	4	6	10	10	12
Package I/O/SERDES Combinations (1mm ball pitch)					
256-ball fpBGA (17 x 17mm)	139/4				
900-ball fpBGA (31 x 31mm)	300/8	378/8			
1020-ball fcBGA (33 x 33mm)[2]		476/16	562/16		
1152-ball fcBGA (35 x 35mm)[3]			604/16	660/16	660/16
1704-ball fcBGA (42.5 x 42.5mm)[3]				904/32	942/32

1. The information in this preliminary data sheet is by definition not final and subject to change. Please consult the Lattice web site and your local Lattice sales office to ensure you have the latest information regarding the specifications for these products as you make critical design decisions.
2. Organic fcBGA converted to organic fcBGA revision 2 per PCN #02A-10.
3. Ceramic fcBGA converted to organic fcBGA per PCN #01A-10.

The LatticeSCM devices add MACO-enabled IP functionality to the base LatticeSC devices. Table 1-2 shows the type and number of each pre-engineered IP core.

Table 1-2. LatticeSCM Family

Device	SCM15	SCM25	SCM40	SCM80	SCM115
flexiMAC Blocks • 1GbE Mode • 10GbE Mode • PCI Express Mode	1	2	2	2	4
SPI4.2 Blocks	1	2	2	2	2
Memory Controller Blocks • DDR/DDR2 DRAM Mode • QDR II/II+ SRAM Mode • RLDRAM I • RLDRAM II CIO/SIO	1	2	2	2	2
Low-Speed CDR Blocks	0	0	2	2	2
PCI Express LTSSM (PHY) Blocks	1	0	2	2	2

Note: See each IP core user's guide for more information about support for specific LatticeSCM devices.

Introduction

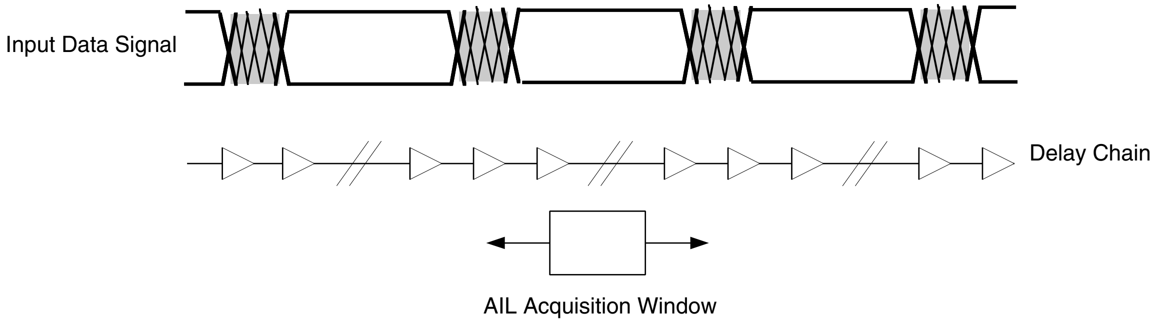
The LatticeSC family of FPGAs combines a high-performance FPGA fabric, high-speed SERDES, high-performance I/Os and large embedded RAM in a single industry leading architecture. This FPGA family is fabricated in a state of the art technology to provide one of the highest performing FPGAs in the industry.

This family of devices includes features to meet the needs of today's communication network systems. These features include SERDES with embedded advance PCS (Physical Coding sub-layer), up to 7.8 Mbits of sysMEM embedded block RAM, dedicated logic to support system level standards such as RAPIDIO, SPI4.2, SFI-4, UTOPIA, XGMII and CSIX. The devices in this family feature clock multiply, divide and phase shift PLLs, numerous

Adaptive Input Logic (AIL) Overview

The Adaptive Input Logic (AIL) provides the ability of the input logic to dynamically find a solution by monitoring multiple samples of the input data. The input data signal from the input buffer is run through a delay chain. Data, transitions, jitter, noise are all contained inside of the delay chain. The AIL will then search the delay chain for a clean sampling point for data. Once found the AIL will monitor and walk with the data dynamically. This novel approach of using a delay chain to create multiple copies of the data provides a lower power solution than oversampling data with a higher speed clock. Figure 2-19 provides a high level view of the AIL methodology.

Figure 2-19. LatticeSC AIL Delay of Input Data Waveform



The AIL slides the acquisition window through the delay chain searching for stable data based solely on data transitions. A specific training pattern is not required to perform this bit alignment, simply data transitions. The size of the acquisition window is user-selectable allowing the AIL to operate over the full range of the PURESPEED I/O range. Based on dynamic user control the AIL can either continuously adjust the window location based on data edge detection or it can be locked to a specific delay.

The AIL operates on single data and double data rate interfaces and is available on most FPGA input pins on the LatticeSC device and all buffer types. The AIL block is low power using only 0.003 mW/MHz typical (6 mW @ 2 Gbps) for PRBS 2^7 data. Multiple AIL inputs can be used to create a bus with a FPGA circuit to realign the bus to a common clock cycle. The FPGA circuit to realign the bus is required and is provided by Lattice as a reference design.

For more information on the LatticeSC AIL please refer to TN1158 LatticeSC PURESPEED I/O Adaptive Input Logic User's Guide.

Input DDR/Shift Block

The DDR/Shift block contains registers and associated logic that support DDR and shift register functions using the high-speed clock and the associated transfer to the low-speed clock domain. It functions as a gearbox allowing high-speed incoming data to be passed into the FPGA fabric. Each PIO supports DDR and x2 shift functions. If desired PIOs A and B or C and D can be combined to form x4 shift functions. The PIOs A and C on the left, right and bottom of the device also contain an optional Adaptive Input Logic (AIL) element. This logic automatically aligns incoming data with the clock allowing for easy design of high-speed interfaces. Figure 2-21 shows a simplified block diagram of the shift register block. The shift block in conjunction with the update and clock divider blocks automatically handles the hand off between the low-speed and high-speed clock domains.

3. **Bottom Side (Banks 4 and 5)**
   These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but true HLVDS and RSDS differential drivers are not available. Adaptive input logic is available on PIOs A or C.

Table 2-8 lists the standards supported by each side.

Table 2-8. I/O Standards Supported by Different Banks

Description	Top Side Banks 1	Right Side Banks 2-3	Bottom Side Banks 4-5	Left Side Banks 6-7
I/O Buffer Type	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver
Output Standards Supported	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]
Input Standards Supported	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Clock Inputs	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Differential Output Support via Emulation	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL
AIL Support	No	Yes	Yes	Yes

1. Input only.
2. Input only. Outputs supported by bussing multiple outputs together.

Supported Standards

The LatticeSC PURESPEED I/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 12, 15, 18, 25 and 33 standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, termination resistance, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL, HSTL, GTL (input only), GTL+ (input only), PCI33, PCIX33, PCIX15, AGP-1X33 and AGP-2X33. Differential standards supported include LVDS, RSDS, BLVDS, MLVDS, LVPECL, differential SSTL and differential HSTL. Tables 12 and 13 show the I/O standards (together with their supply and reference voltages) supported by the LatticeSC devices. The tables also provide the available internal termination schemes. For further information on utilizing the PURESPEED I/O buffer to support a variety of standards please see details of additional technical documentation at the end of this data sheet.

this allows for easy integration with the rest of the system. These capabilities make the LatticeSC ideal for many multiple power supply and hot-swap applications. The maximum current during hot socketing is 4mA. See Hot Socketing Specifications in Chapter 3 of this data sheet.

Power-Up Requirements

To prevent high power supply and input pin currents, each VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies must have a monotonic ramp up time of 75 ms or less to reach its minimum operating voltage. Apart from VCC and VCC12, which have an additional requirement, and VCCIO and VCCAUX, which also have an additional requirement, the VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies can ramp up in any order, with no restriction on the time between them. However, the ramp time for each must be 75 ms or less. Configuration of the device will not proceed until the last power supply has reached its minimum operating voltage.

Additional Requirement for VCC and VCC12:

VCC12 must always be higher than VCC. This condition must be maintained at ALL times, including during power-up and power-down. Note that for 1.2V only operation, it is advisable to source both of these supplies from the same power supply.

Additional Requirement for VCCIO and VCCAUX:

If any VCCIOs are 1.2/1.5/1.8V, then VCCAUX MUST be applied before them. If any VCCIO is 1.2/1.5/1.8V and is powered up before VCCAUX, then when VCCAUX is powered up, it may drag VCCIO up with it as it crosses through the VCCIO value. (Note: If the VCCIO supply is capable of sinking current, as well as the more usual sourcing capability, this behavior is eliminated. However, the amount of current that the supply needs to sink is unknown and is likely to be in the hundreds of milliamps range).

Power-Down Requirements

To prevent high power supply and input pin currents, power must be removed monotonically from either VCC or VCCAUX (and must reach the power-down trip point of 0.5V for VCC, 0.95V for VCCAUX) before power is removed monotonically from VCC12, any of the VCCIOs, or VCCJ. Note that VCC12 can be removed at the same time as VCC, but it cannot be removed earlier. In many applications, VCC and VCC12 will be sourced from the same power supply and so will be removed together. For systems where disturbance of the user pins is a don't care condition, the power supplies can be removed in any order as long as they power down monotonically within 200ms of each other.

Additionally, if any banks have VCCIO=3.3V nominal (potentially banks 1, 4, 5) then VCCIO for those banks must not be lower than VCCAUX during power-down. The normal variation in ramp-up times of power supplies and voltage regulators is not a concern here.

Note: The SERDES power supplies are NOT included in these requirements and have no specific sequencing requirements. However, when using the SERDES with VDDIB or VDDOB that is greater than 1.2V (1.5V nominal for example), the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in the ramp-up times of power supplies and voltage regulators is not a concern here.

SERDES Power Supply Sequencing Requirements

When using the SERDES with 1.5V VDDIB or VDDOB supplies, the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and the 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in ramp-up times of power supples and voltage regulators is not a concern.

Additional Requirement for SERDES Power Supply

All VCC12 pins need to be connected on all devices independent of functionality used on the device. This analog supply is used by both the RX and TX portions of the SERDES and is used to control the core SERDES logic regardless of the SERDES being used in the design. VDDIB and VDDOB are used as supplies for the terminations on the CML input and output buffers. If a particular channel is not used, these can be UNCONNECTED (floating).

Power Supply Ramp Rates

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
t_{RAMP}	Power supply ramp rates for all power supplies	Over process, voltage, temperature	3.45	—	—	mV/µs
			—	—	75	ms

1. See the Power-up and Power-Down requirements section for more details on power sequencing.
2. From 0.5V to minimum operating voltage.

Hot Socketing Specifications[1]

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Programmable and dedicated Input or I/O leakage current[2, 3, 4, 5, 6]	0 <= V_{IN} <= V_{IH} (MAX)	—	—	±1500	µA
I_{HDIN}	SERDES average input current when device powered down and inputs driven[7]		—	—	4	mA

1. See Hot Socket power up/down information in Chapter 2 of this document.
2. Assumes monotonic rise/fall rates for all power supplies.
3. Sensitive to power supply sequencing as described in hot socketing section.
4. Assumes power supplies are between 0 and maximum recommended operations conditions.
5. IDK is additive to I_{PU}, I_{PD} or I_{BH}.
6. Represents DC conditions. For the first 20ns after hot insertion, current specification is 8 mA.
7. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed VDDOB of 1.575V, 8b/10b data and internal AC coupling.

DC Electrical Characteristics[5]

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.[3]	Typ.	Max.	Units
I_{IL}, I_{IH}[1]	Input or I/O Low leakage	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	10	µA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7\ V_{CCIO}$	-30	—	-210	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\leq V_{IN} \leq V_{IH}$ (MAX)	30	—	210	µA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	210	µA
I_{BHLH}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	-210	µA
I_{CL}	PCI Low Clamp Current	$-3 < V_{IN} \leq -1$	$-25 + (V_{IN} + 1)/0.015$	—	—	mA
I_{CH}	PCI High Clamp Current	$V_{CC} + 4 > V_{IN} \geq V_{CC} + 1$	$25 + (V_{IN} - V_{CC} -1)/0.015$	—	—	mA
V_{BHT}	Bus Hold trip Points	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C3[2]	Dedicated Input Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f = 1.0MHz
3. I_{PU}, I_{PD}, I_{BHLS} and I_{BHHS} have minimum values of 15 or -15µA if V_{CCIO} is set to 1.2V nominal.
4. This table does not apply to SERDES pins.
5. For programmable I/Os.

RSDS

Over Recommended Operating Conditions

Parameter Symbol	Description	Min.	Typ.	Max.	Units
V_{OD}	Output voltage, differential, R_T = 100 ohms	100	200	600	mV
V_{OS}	Output voltage, common mode	0.5	1.2	1.5	V
I_{RSDS}	Differential driver output current	1	2	6	mA
V_{THD}	Input voltage differential	100	—	—	mV
V_{CM}	Input common mode voltage	0.3	—	1.5	V
T_R, T_F	Output rise and fall times, 20% to 80%	—	500	—	ps
T_{ODUTY}	Output clock duty cycle	45	50	55	%

Note: Data is for 2mA drive. Other differential driver current options are available.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
D[n:0]	I/O	In parallel configuration modes, D[7:0] receives configuration data, and each pin is pull-up enabled. For slave serial mode, D0 is the data input. D[7:3] is the output internal status for peripheral mode when RDN is low. D[7:0] is also the first byte of MPI data pins. In MPI configuration mode, MPI selectable data bus width from 8 and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
DP[m:0]	I/O	MPI selectable parity data bus width from 1, 2, and 3-bit DP[0] for D[7:0], DP[1] for D[15:8], and DP[2] for D[23:16].
BUSYN/RCLK/SCK	O	During configuration in peripheral mode, high on BUSYN indicates another byte can be written to the FPGA. If a read operation is done when the device is selected, the same status is also available on D[7] in asynchronous peripheral mode. During configuration in slave parallel mode, low on BUSYN inhibits the external host from sending new data. The output is used by slave parallel and master serial modes only for decompression. During configuration in master parallel and master byte modes, RCLK is a read clock output signal to an external memory. The RCLK frequency is the same as CCLK when used with uncompressed bitstreams. RCLK will be 1/8 the frequency of CCLK when the bitstream is compressed. During configuration in SPI modes, SCK is generated by the device and connected to the CLK input of the FLASH memory.
MPI Interface (Dedicated pin)		
MPI_IRQ_N	O	MPI Interrupt request active low signal is controlled by system bus interrupt controller and may be sourced from any bus error or MPI configuration error. It can be connected to one of MPC860 IRQ pins.
MPI Interface (User I/O if MPI is not used.)		
MPI_CS0N MPI_CS1	I	MPI chip select pins, active low on MPI_CS0N while active high on MPI_CS1. Both have to be active during the whole transfer data phase. During transfer address phase, both can be inactive so that the decoding for them from address can be slow. If they are active during address phase, one cycle can be saved for sync read.
MPI_CLK	I	This is the PowerPC bus clock. It can be a source of the clock for embedded system bus. If MPI_CLK is used as system bus clock, MPI will be set into sync mode by default. All of the operation on PowerPC side of MPI are synchronized to the rising edge of this clock.
MPI_TSIZ[1:0]	I	Driven by a bus master to indicate the data transfer size for the transaction. 01 for byte, 10 for half-word, and 00 for word.
MPI_WR_N	I	Driven high indicates that a read access is in progress. Driven low indicates that a write access is in process.
MPI_BURST	I	Driven active low indicates that a burst transfer is in progress. Driven high indicates that the current transfer is not a burst.
MPI_BDIP	I	Active low “Burst Data in Process” is driven by a PowerPC processor. Asserted indicates that the second beat in front of the current one is requested by the master. Negated before the burst transfer ends to abort the burst data phase.

Pin Information Summary (Cont.)

Pin Type		1152 fcBGA			1704 fcBGA	
		LFSC/M40	LFSC/M80	LFSC/M115	LFSC/M80	LFSC/M115
Single Ended User I/O		604	660	660	904	942
Differential Pair User I/O		302	330	330	452	470
LVDS Output Pairs		78	102	102	114	132
Configuration	Dedicated	11	11	11	11	11
	Muxes/MPI sysBus	72	72	72	72	72
JTAG (excluding VCCJ)		4	4	4	4	4
Dedicated Pins		4	4	4	4	4
VCC		44	44	44	76	76
VCC12		52	52	52	88	88
VCCAUX		38	38	38	52	52
VCCIO	Bank 1	10	10	10	10	10
	Bank 2	9	9	9	12	12
	Bank 3	12	12	12	14	14
	Bank 4	12	12	12	14	14
	Bank 5	12	12	12	14	14
	Bank 6	12	12	12	14	14
	Bank 7	9	9	9	12	12
VTT	Bank 2	3	3	3	4	4
	Bank 3	3	3	3	4	4
	Bank 4	3	3	3	5	5
	Bank 5	3	3	3	5	5
	Bank 6	3	3	3	4	4
	Bank 7	3	3	3	4	4
GND		130	130	130	184	184
NC		62	6	6	52	14
Single Ended User / Differential I/O per Bank	Bank 1	80/40	80/40	80/40	80/40	80/40
	Bank 2	60/30	76/38	76/38	96/48	103/51
	Bank 3	96/48	108/54	108/54	132/66	144/72
	Bank 4	106/53	106/53	106/53	184/92	184/92
	Bank 5	106/53	106/53	106/53	184/92	184/92
	Bank 6	96/48	108/54	108/54	132/66	144/72
	Bank 7	60/30	76/38	76/38	96/48	103/51
LVDS Output Pairs Per Bank	Bank 2	15	21	21	24	27
	Bank 3	24	30	30	33	39
	Bank 6	24	30	30	33	39
	Bank 7	15	21	21	24	27
VCCJ		1	1	1	1	1
SERDES (signal + power supply)		108	108	108	212	212
Total		1152	1152	1152	1704	1704

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AJ27	GND	-		GND	-	
AF23	GND	-		GND	-	
AF22	GND	-		GND	-	
AE27	GND	-		GND	-	
AA27	GND	-		GND	-	
AB29	GND	-		GND	-	
Y26	GND	-		GND	-	
AC30	GND	-		GND	-	
Y29	GND	-		GND	-	
F30	GND	-		GND	-	
E27	GND	-		GND	-	
F27	GND	-		GND	-	
P25	GND	-		GND	-	
H29	GND	-		GND	-	
K29	GND	-		GND	-	
R24	GND	-		GND	-	
M28	GND	-		GND	-	
J27	GND	-		GND	-	
N26	GND	-		GND	-	
E20	GND	-		GND	-	
E21	GND	-		GND	-	
F21	GND	-		GND	-	
F23	GND	-		GND	-	
G23	GND	-		GND	-	
D21	GND	-		GND	-	
D20	GND	-		GND	-	
E18	GND	-		GND	-	
C20	GND	-		GND	-	
C11	GND	-		GND	-	
A12	GND	-		GND	-	
E11	GND	-		GND	-	
F8	GND	-		GND	-	
G8	GND	-		GND	-	
D11	GND	-		GND	-	
D10	GND	-		GND	-	
H7	GND	-		GND	-	
F10	GND	-		GND	-	
E10	GND	-		GND	-	
AC16	NC	-		NC	-	
J22	VCC	-		VCC	-	
J9	VCC	-		VCC	-	
B2	NC	-		NC	-	
C2	RESPN_ULC	-		RESPN_ULC	-	
C29	RESPN_URC	-		RESPN_URC	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
F19	PT24A	1	MPI_TEA	PT30A	1	MPI_TEA
J18	PT23D	1	D14/MPI_DATA14	PT28D	1	D14/MPI_DATA14
K18	PT23C	1	DP1/MPI_PAR1	PT28C	1	DP1/MPI_PAR1
E20	PT23B	1	A21/MPI_BURST	PT27B	1	A21/MPI_BURST
F20	PT23A	1	D15/MPI_DATA15	PT27A	1	D15/MPI_DATA15
C23	B_REFCLKP_L	-		B_REFCLKP_L	-	
D23	B_REFCLKN_L	-		B_REFCLKN_L	-	
B23	VCC12	-		VCC12	-	
H21	B_VDDIB3_L	-		B_VDDIB3_L	-	
F21	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
G21	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
A21	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
B21	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
D21	B_VDDOB3_L	-		B_VDDOB3_L	-	
B22	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
D22	B_VDDOB2_L	-		B_VDDOB2_L	-	
A22	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
G22	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
F22	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
H22	B_VDDIB2_L	-		B_VDDIB2_L	-	
H24	B_VDDIB1_L	-		B_VDDIB1_L	-	
G23	B_HDINP1_L	-	PCS 361 CH 1 IN P	B_HDINP1_L	-	PCS 361 CH 1 IN P
H23	B_HDINN1_L	-	PCS 361 CH 1 IN N	B_HDINN1_L	-	PCS 361 CH 1 IN N
A24	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P
B24	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N
D24	B_VDDOB1_L	-		B_VDDOB1_L	-	
B25	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N
D25	B_VDDOB0_L	-		B_VDDOB0_L	-	
A25	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P
G25	B_HDINN0_L	-	PCS 361 CH 0 IN N	B_HDINN0_L	-	PCS 361 CH 0 IN N
F25	B_HDINP0_L	-	PCS 361 CH 0 IN P	B_HDINP0_L	-	PCS 361 CH 0 IN P
H25	B_VDDIB0_L	-		B_VDDIB0_L	-	
H26	A_VDDIB3_L	-		A_VDDIB3_L	-	
F26	A_HDINP3_L	-	PCS 360 CH 3 IN P	A_HDINP3_L	-	PCS 360 CH 3 IN P
G26	A_HDINN3_L	-	PCS 360 CH 3 IN N	A_HDINN3_L	-	PCS 360 CH 3 IN N
A26	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
B26	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
D26	A_VDDOB3_L	-		A_VDDOB3_L	-	
B27	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
D27	A_VDDOB2_L	-		A_VDDOB2_L	-	
A27	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
G27	A_HDINN2_L	-	PCS 360 CH 2 IN N	A_HDINN2_L	-	PCS 360 CH 2 IN N
F27	A_HDINP2_L	-	PCS 360 CH 2 IN P	A_HDINP2_L	-	PCS 360 CH 2 IN P
H27	A_VDDIB2_L	-		A_VDDIB2_L	-	
F29	A_VDDIB1_L	-		A_VDDIB1_L	-	
G28	A_HDINP1_L	-	PCS 360 CH 1 IN P	A_HDINP1_L	-	PCS 360 CH 1 IN P
H28	A_HDINN1_L	-	PCS 360 CH 1 IN N	A_HDINN1_L	-	PCS 360 CH 1 IN N
A29	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
B29	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
D29	A_VDDOB1_L	-		A_VDDOB1_L	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P10	GND	-		GND	-	
P13	GND	-		GND	-	
P15	GND	-		GND	-	
P18	GND	-		GND	-	
P20	GND	-		GND	-	
P24	GND	-		GND	-	
R12	GND	-		GND	-	
R14	GND	-		GND	-	
R16	GND	-		GND	-	
R17	GND	-		GND	-	
R19	GND	-		GND	-	
R21	GND	-		GND	-	
R26	GND	-		GND	-	
R6	GND	-		GND	-	
T15	GND	-		GND	-	
T18	GND	-		GND	-	
T30	GND	-		GND	-	
T4	GND	-		GND	-	
U15	GND	-		GND	-	
U18	GND	-		GND	-	
U29	GND	-		GND	-	
U3	GND	-		GND	-	
V12	GND	-		GND	-	
V14	GND	-		GND	-	
V16	GND	-		GND	-	
V17	GND	-		GND	-	
V19	GND	-		GND	-	
V21	GND	-		GND	-	
V27	GND	-		GND	-	
V7	GND	-		GND	-	
W13	GND	-		GND	-	
W15	GND	-		GND	-	
W18	GND	-		GND	-	
W20	GND	-		GND	-	
W23	GND	-		GND	-	
W9	GND	-		GND	-	
Y12	GND	-		GND	-	
Y14	GND	-		GND	-	
Y19	GND	-		GND	-	
Y21	GND	-		GND	-	
Y30	GND	-		GND	-	
Y4	GND	-		GND	-	
N13	VCC	-		VCC	-	
N15	VCC	-		VCC	-	
N16	VCC	-		VCC	-	
N17	VCC	-		VCC	-	
N18	VCC	-		VCC	-	
N20	VCC	-		VCC	-	
P14	VCC	-		VCC	-	
P16	VCC	-		VCC	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2]

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G34	A_REFCLKP_L	-		A_REFCLKP_L	-	
H34	A_REFCLKN_L	-		A_REFCLKN_L	-	
N30	VCC12	-		VCC12	-	
H33	RESP_ULC	-		RESP_ULC	-	
P25	RESETN	1		RESETN	1	
P26	TSALLN	1		TSALLN	1	
P31	DONE	1		DONE	1	
P23	INITN	1		INITN	1	
P30	M0	1		M0	1	
P22	M1	1		M1	1	
P24	M2	1		M2	1	
R22	M3	1		M3	1	
J37	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
J38	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
P32	PL16C	7		PL15C	7	
R32	PL16D	7		PL15D	7	
G40	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
H40	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
N33	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
P33	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
G41	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
H41	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
T29	PL18C	7		PL18C	7	
U29	PL18D	7	VREF2_7	PL18D	7	VREF2_7
G42	PL20A	7		PL19A	7	
H42	PL20B	7		PL19B	7	
M34	PL20C	7		PL19C	7	
M35	PL20D	7		PL19D	7	
K37	PL21A	7		PL26A	7	
L37	PL21B	7		PL26B	7	
N34	PL21C	7		PL26C	7	
P34	PL21D	7		PL26D	7	
K38	PL22A	7		PL30A	7	
L38	PL22B	7		PL30B	7	
T33	PL22C	7		PL30C	7	
R33	PL22D	7		PL30D	7	
J41	PL24A	7		PL34A	7	
K41	PL24B	7		PL34B	7	
U31	PL24C	7		PL34C	7	
V31	PL24D	7		PL34D	7	
K42	PL25A	7		PL38A	7	
J42	PL25B	7		PL38B	7	
J36	PL25C	7		PL38C	7	
K36	PL25D	7		PL38D	7	
N38	PL26A	7		PL40A	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

	LFSC/M80			LFSC/M115		
Ball Number	**Ball Function**	**VCCIO Bank**	**Dual Function**	**Ball Function**	**VCCIO Bank**	**Dual Function**
AD33	PL59D	6		PL73D	6	
AA38	PL60A	6		PL74A	6	
AB38	PL60B	6		PL74B	6	
AC29	PL60C	6		PL74C	6	
AD29	PL60D	6		PL74D	6	
AA41	PL61A	6		PL75A	6	
AB41	PL61B	6		PL75B	6	
AC34	PL61C	6		PL75C	6	
AD34	PL61D	6		PL75D	6	
AA42	PL63A	6		PL77A	6	
AB42	PL63B	6		PL77B	6	
AC37	PL63C	6		PL77C	6	
AD37	PL63D	6		PL77D	6	
AC38	PL64A	6		PL78A	6	
AD38	PL64B	6		PL78B	6	
AD36	PL64C	6		PL78C	6	
AE36	PL64D	6		PL78D	6	
AC39	PL65A	6		PL79A	6	
AD39	PL65B	6		PL79B	6	
AD35	PL65C	6		PL79C	6	
AE35	PL65D	6		PL79D	6	
AC40	PL67A	6		PL81A	6	
AD40	PL67B	6		PL81B	6	
AE37	PL67C	6		PL81C	6	
AF37	PL67D	6		PL81D	6	
AC41	PL68A	6		PL82A	6	
AD41	PL68B	6		PL82B	6	
AE34	PL68C	6		PL82C	6	
AF34	PL68D	6		PL82D	6	
AC42	PL69A	6		PL83A	6	
AD42	PL69B	6		PL83B	6	
AE33	PL69C	6		PL83C	6	
AF33	PL69D	6		PL83D	6	
AE38	PL72A	6		PL86A	6	
AF38	PL72B	6		PL86B	6	
AE32	PL72C	6		PL86C	6	
AF32	PL72D	6		PL86D	6	
AE41	PL73A	6		PL87A	6	
AF41	PL73B	6		PL87B	6	
AE31	PL73C	6		PL87C	6	
AF31	PL73D	6		PL87D	6	
AE42	PL74A	6		PL88A	6	
AF42	PL74B	6		PL88B	6	
AG37	PL74C	6		PL88C	6	
AH37	PL74D	6		PL88D	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AP26	PB41C	5		PB43C	5	
AN26	PB41D	5		PB43D	5	
AY30	PB43A	5		PB45A	5	
AY29	PB43B	5		PB45B	5	
AU30	PB43C	5		PB45C	5	
AU31	PB43D	5		PB45D	5	
AV27	PB44A	5		PB46A	5	
AV26	PB44B	5		PB46B	5	
AT28	PB44C	5		PB46C	5	
AT27	PB44D	5		PB46D	5	
BA29	PB45A	5		PB47A	5	
BA28	PB45B	5		PB47B	5	
AL25	PB45C	5		PB47C	5	
AM25	PB45D	5		PB47D	5	
BB29	PB47A	5		PB49A	5	
BB28	PB47B	5		PB49B	5	
AN25	PB47C	5		PB49C	5	
AP25	PB47D	5		PB49D	5	
AY27	PB48A	5	PCLKT5_3	PB50A	5	PCLKT5_3
AY26	PB48B	5	PCLKC5_3	PB50B	5	PCLKC5_3
AT25	PB48C	5	PCLKT5_4	PB50C	5	PCLKT5_4
AT24	PB48D	5	PCLKC5_4	PB50D	5	PCLKC5_4
AW27	PB49A	5	PCLKT5_5	PB51A	5	PCLKT5_5
AW26	PB49B	5	PCLKC5_5	PB51B	5	PCLKC5_5
AU29	PB49C	5		PB51C	5	
AU28	PB49D	5		PB51D	5	
BB27	PB51A	5	PCLKT5_0	PB53A	5	PCLKT5_0
BB26	PB51B	5	PCLKC5_0	PB53B	5	PCLKC5_0
AR25	PB51C	5		PB53C	5	
AR24	PB51D	5	VREF2_5	PB53D	5	VREF2_5
BA27	PB52A	5	PCLKT5_1	PB54A	5	PCLKT5_1
BA26	PB52B	5	PCLKC5_1	PB54B	5	PCLKC5_1
AP24	PB52C	5	PCLKT5_6	PB54C	5	PCLKT5_6
AN24	PB52D	5	PCLKC5_6	PB54D	5	PCLKC5_6
AV25	PB53A	5	PCLKT5_2	PB55A	5	PCLKT5_2
AV24	PB53B	5	PCLKC5_2	PB55B	5	PCLKC5_2
AU27	PB53C	5	PCLKT5_7	PB55C	5	PCLKT5_7
AU26	PB53D	5	PCLKC5_7	PB55D	5	PCLKC5_7
BA25	PB55A	5		PB57A	5	
BA24	PB55B	5		PB57B	5	
AU24	PB55C	5		PB57C	5	
AU25	PB55D	5		PB57D	5	
BB24	PB56A	5		PB58A	5	
BB25	PB56B	5		PB58B	5	
AM23	PB56C	5		PB58C	5	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

	LFSC/M80			LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AE1	PR74A	3		PR88A	3	
AF12	PR73D	3		PR87D	3	
AE12	PR73C	3		PR87C	3	
AF2	PR73B	3		PR87B	3	
AE2	PR73A	3		PR87A	3	
AF11	PR72D	3		PR86D	3	
AE11	PR72C	3		PR86C	3	
AF5	PR72B	3		PR86B	3	
AE5	PR72A	3		PR86A	3	
AF10	PR69D	3		PR83D	3	
AE10	PR69C	3		PR83C	3	
AD1	PR69B	3		PR83B	3	
AC1	PR69A	3		PR83A	3	
AF9	PR68D	3		PR82D	3	
AE9	PR68C	3		PR82C	3	
AD2	PR68B	3		PR82B	3	
AC2	PR68A	3		PR82A	3	
AF6	PR67D	3		PR81D	3	
AE6	PR67C	3		PR81C	3	
AD3	PR67B	3		PR81B	3	
AC3	PR67A	3		PR81A	3	
AE8	PR65D	3		PR79D	3	
AD8	PR65C	3		PR79C	3	
AD4	PR65B	3		PR79B	3	
AC4	PR65A	3		PR79A	3	
AE7	PR64D	3		PR78D	3	
AD7	PR64C	3		PR78C	3	
AD5	PR64B	3		PR78B	3	
AC5	PR64A	3		PR78A	3	
AD6	PR63D	3		PR77D	3	
AC6	PR63C	3		PR77C	3	
AB1	PR63B	3		PR77B	3	
AA1	PR63A	3		PR77A	3	
AD9	PR61D	3		PR75D	3	
AC9	PR61C	3		PR75C	3	
AB2	PR61B	3		PR75B	3	
AA2	PR61A	3		PR75A	3	
AD14	PR60D	3		PR74D	3	
AC14	PR60C	3		PR74C	3	
AB5	PR60B	3		PR74B	3	
AA5	PR60A	3		PR74A	3	
AD10	PR59D	3		PR73D	3	
AC10	PR59C	3		PR73C	3	
Y1	PR59B	3		PR73B	3	
W1	PR59A	3		PR73A	3	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

	LFSC/M80			LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D1	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
F1	VCC12	-		VCC12	-	
A3	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
E1	A_VDDOB0_R	-		A_VDDOB0_R	-	
B3	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
C2	A_VDDOB1_R	-		A_VDDOB1_R	-	
A4	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
B2	VCC12	-		VCC12	-	
B4	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
E3	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
D3	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
M10	VCC12	-		VCC12	-	
E2	A_VDDIB1_R	-		A_VDDIB1_R	-	
J11	VCC12	-		VCC12	-	
M11	A_VDDIB2_R	-		A_VDDIB2_R	-	
D4	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
E4	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
K9	VCC12	-		VCC12	-	
A5	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
D2	A_VDDOB2_R	-		A_VDDOB2_R	-	
B5	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
L10	A_VDDOB3_R	-		A_VDDOB3_R	-	
B6	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
G6	VCC12	-		VCC12	-	
A6	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
E5	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
D5	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
K12	VCC12	-		VCC12	-	
L13	A_VDDIB3_R	-		A_VDDIB3_R	-	
N14	VCC12	-		VCC12	-	
F9	B_VDDIB0_R	-		B_VDDIB0_R	-	
D6	B_HDINP0_R	-	PCS 3E1 CH 0 IN P	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
E6	B_HDINN0_R	-	PCS 3E1 CH 0 IN N	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
J8	VCC12	-		VCC12	-	
B7	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
G4	B_VDDOB0_R	-		B_VDDOB0_R	-	
A7	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
K8	B_VDDOB1_R	-		B_VDDOB1_R	-	
A8	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L9	VCC12	-		VCC12	-	
B8	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
E7	B_HDINN1_R	-	PCS 3E1 CH 1 IN N	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
D7	B_HDINP1_R	-	PCS 3E1 CH 1 IN P	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
F10	VCC12	-		VCC12	-	
K13	B_VDDIB1_R	-		B_VDDIB1_R	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
A26	D_HDOUTN2_L	-	PCS 363 CH 2 OUT N	D_HDOUTN2_L	-	PCS 363 CH 2 OUT N
C34	D_VDDOB2_L	-		D_VDDOB2_L	-	
B26	D_HDOUTP2_L	-	PCS 363 CH 2 OUT P	D_HDOUTP2_L	-	PCS 363 CH 2 OUT P
C32	VCC12	-		VCC12	-	
E27	D_HDINN2_L	-	PCS 363 CH 2 IN N	D_HDINN2_L	-	PCS 363 CH 2 IN N
D27	D_HDINP2_L	-	PCS 363 CH 2 IN P	D_HDINP2_L	-	PCS 363 CH 2 IN P
G25	D_VDDIB2_L	-		D_VDDIB2_L	-	
F29	VCC12	-		VCC12	-	
H26	D_VDDIB1_L	-		D_VDDIB1_L	-	
F30	VCC12	-		VCC12	-	
D28	D_HDINP1_L	-	PCS 363 CH 1 IN P	D_HDINP1_L	-	PCS 363 CH 1 IN P
E28	D_HDINN1_L	-	PCS 363 CH 1 IN N	D_HDINN1_L	-	PCS 363 CH 1 IN N
B27	D_HDOUTP1_L	-	PCS 363 CH 1 OUT P	D_HDOUTP1_L	-	PCS 363 CH 1 OUT P
F36	VCC12	-		VCC12	-	
A27	D_HDOUTN1_L	-	PCS 363 CH 1 OUT N	D_HDOUTN1_L	-	PCS 363 CH 1 OUT N
F35	D_VDDOB1_L	-		D_VDDOB1_L	-	
A28	D_HDOUTN0_L	-	PCS 363 CH 0 OUT N	D_HDOUTN0_L	-	PCS 363 CH 0 OUT N
M30	D_VDDOB0_L	-		D_VDDOB0_L	-	
B28	D_HDOUTP0_L	-	PCS 363 CH 0 OUT P	D_HDOUTP0_L	-	PCS 363 CH 0 OUT P
F37	VCC12	-		VCC12	-	
E29	D_HDINN0_L	-	PCS 363 CH 0 IN N	D_HDINN0_L	-	PCS 363 CH 0 IN N
D29	D_HDINP0_L	-	PCS 363 CH 0 IN P	D_HDINP0_L	-	PCS 363 CH 0 IN P
H27	D_VDDIB0_L	-		D_VDDIB0_L	-	
G28	VCC12	-		VCC12	-	
J28	C_REFCLKP_L	-		C_REFCLKP_L	-	
K28	C_REFCLKN_L	-		C_REFCLKN_L	-	
F32	VCC12	-		VCC12	-	
G29	C_VDDIB3_L	-		C_VDDIB3_L	-	
C31	VCC12	-		VCC12	-	
D30	C_HDINP3_L	-	PCS 362 CH 3 IN P	C_HDINP3_L	-	PCS 362 CH 3 IN P
E30	C_HDINN3_L	-	PCS 362 CH 3 IN N	C_HDINN3_L	-	PCS 362 CH 3 IN N
B29	C_HDOUTP3_L	-	PCS 362 CH 3 OUT P	C_HDOUTP3_L	-	PCS 362 CH 3 OUT P
F38	VCC12	-		VCC12	-	
A29	C_HDOUTN3_L	-	PCS 362 CH 3 OUT N	C_HDOUTN3_L	-	PCS 362 CH 3 OUT N
J33	C_VDDOB3_L	-		C_VDDOB3_L	-	
A30	C_HDOUTN2_L	-	PCS 362 CH 2 OUT N	C_HDOUTN2_L	-	PCS 362 CH 2 OUT N
K33	C_VDDOB2_L	-		C_VDDOB2_L	-	
B30	C_HDOUTP2_L	-	PCS 362 CH 2 OUT P	C_HDOUTP2_L	-	PCS 362 CH 2 OUT P
J34	VCC12	-		VCC12	-	
F31	C_HDINN2_L	-	PCS 362 CH 2 IN N	C_HDINN2_L	-	PCS 362 CH 2 IN N
E31	C_HDINP2_L	-	PCS 362 CH 2 IN P	C_HDINP2_L	-	PCS 362 CH 2 IN P
G30	C_VDDIB2_L	-		C_VDDIB2_L	-	
H28	VCC12	-		VCC12	-	
C37	C_VDDIB1_L	-		C_VDDIB1_L	-	
H30	VCC12	-		VCC12	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D32	C_HDINP1_L	-	PCS 362 CH 1 IN P	C_HDINP1_L	-	PCS 362 CH 1 IN P
E32	C_HDINN1_L	-	PCS 362 CH 1 IN N	C_HDINN1_L	-	PCS 362 CH 1 IN N
B31	C_HDOUTP1_L	-	PCS 362 CH 1 OUT P	C_HDOUTP1_L	-	PCS 362 CH 1 OUT P
K32	VCC12	-		VCC12	-	
A31	C_HDOUTN1_L	-	PCS 362 CH 1 OUT N	C_HDOUTN1_L	-	PCS 362 CH 1 OUT N
L32	C_VDDOB1_L	-		C_VDDOB1_L	-	
A32	C_HDOUTN0_L	-	PCS 362 CH 0 OUT N	C_HDOUTN0_L	-	PCS 362 CH 0 OUT N
M31	C_VDDOB0_L	-		C_VDDOB0_L	-	
B32	C_HDOUTP0_L	-	PCS 362 CH 0 OUT P	C_HDOUTP0_L	-	PCS 362 CH 0 OUT P
H37	VCC12	-		VCC12	-	
E33	C_HDINN0_L	-	PCS 362 CH 0 IN N	C_HDINN0_L	-	PCS 362 CH 0 IN N
D33	C_HDINP0_L	-	PCS 362 CH 0 IN P	C_HDINP0_L	-	PCS 362 CH 0 IN P
G31	C_VDDIB0_L	-		C_VDDIB0_L	-	
J29	VCC12	-		VCC12	-	
L29	B_REFCLKP_L	-		B_REFCLKP_L	-	
M29	B_REFCLKN_L	-		B_REFCLKN_L	-	
J31	VCC12	-		VCC12	-	
H31	B_VDDIB3_L	-		B_VDDIB3_L	-	
J30	VCC12	-		VCC12	-	
D34	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
E34	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
B33	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
H38	VCC12	-		VCC12	-	
A33	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
C38	B_VDDOB3_L	-		B_VDDOB3_L	-	
A34	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
L31	B_VDDOB2_L	-		B_VDDOB2_L	-	
B34	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
G38	VCC12	-		VCC12	-	
E35	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
D35	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
H32	B_VDDIB2_L	-		B_VDDIB2_L	-	
K29	VCC12	-		VCC12	-	
K30	B_VDDIB1_L	-		B_VDDIB1_L	-	
F33	VCC12	-		VCC12	-	
D36	B_HDINP1_L	-	PCS 361 CH 1 IN P	B_HDINP1_L	-	PCS 361 CH 1 IN P
E36	B_HDINN1_L	-	PCS 361 CH 1 IN N	B_HDINN1_L	-	PCS 361 CH 1 IN N
B35	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P
L34	VCC12	-		VCC12	-	
A35	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N
K35	B_VDDOB1_L	-		B_VDDOB1_L	-	
A36	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N
G39	B_VDDOB0_L	-		B_VDDOB0_L	-	
B36	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P
J35	VCC12	-		VCC12	-	

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1101 - Power Estimation and Management for LatticeSC Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

LatticeSC/M Family Data Sheet Supplemental Information

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For Further Information

For further information about the flexiPCS, see the LatticeSC/M Family flexiPCS Data Sheet.

A variety of technical notes for the LatticeSC/M family are also available on the Lattice Semiconductor website at www.latticesemi.com.

- LatticeSC PURESPEED I/O Usage Guide (TN1088)
- LatticeSC PURESPEED I/O Adaptive Input Logic User's Guide (TN1158)
- LatticeSC sysCLOCK PLL/DLL User's Guide (TN1098)
- On-Chip Memory Usage Guide for LatticeSC Devices (TN1094)
- LatticeSC/M DDR/DDR2 SDRAM Memory Interface User's Guide (TN1099)
- LatticeSC QDRII/II+ SRAM Memory Interface User's Guide (TN1096)
- LatticeSC sysCONFIG Usage Guide (TN1080)
- LatticeSC MPI/System Bus (TN1085)
- SPI Serial Flash Programming Using ispJTAG in LatticeSC Devices (TN1100)
- Power Estimation and Management for LatticeSC Devices (TN1101)
- LatticeSC SERDES Jitter (TN1084)
- LatticeSC FPGAs: Implementing 3.3V Interfaces in 2.5V VCCIO Banks (TN1110)
- Lattice PCI Express Basic Demo User's Guide (UG08)
- LatticeSC flexiPCS/SERDES Design Guide (TN1145)
- Temperature Sensing Diode in LatticeSC Devices (TN1115)
- SPI4.2 Interoperability Between ORSPI4 and LatticeSC Devices (TN1116)

For further information on Interface standards refer to the following websites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- Optical Interface (SPI-4.2, XSBI, CSIX and XGMII): www.oiforum.com
- RAPIDIO: www.rapidio.org
- PCI/PCIX: ww.pcisig.com